

Fig. 11 a Power dissipation per diode vs. forward current and ambient temperature

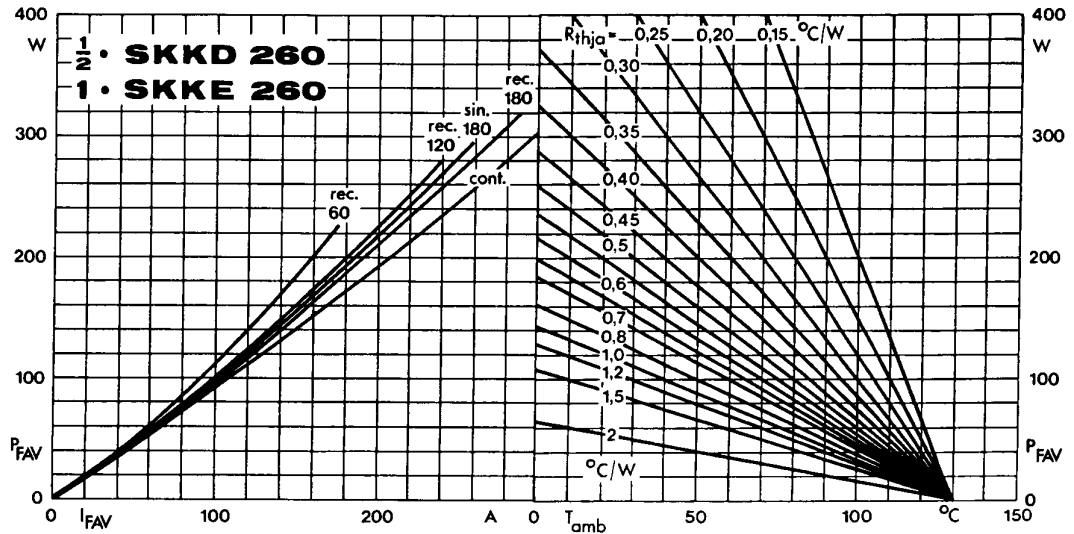


Fig. 11 b Power dissipation per diode vs. forward current and ambient temperature

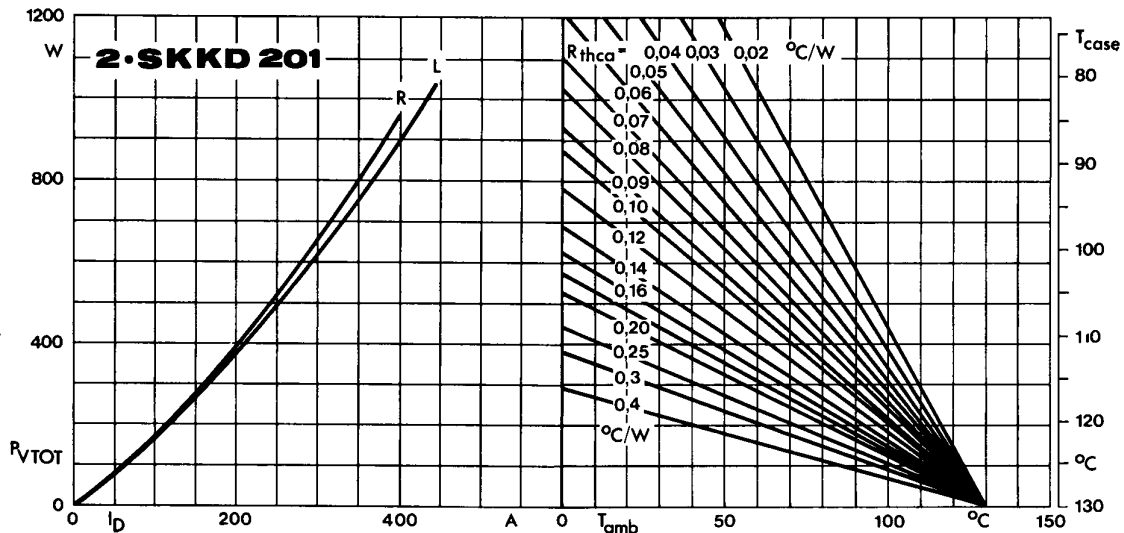


Fig. 12 a Power dissipation of two modules vs. direct current and case temperature

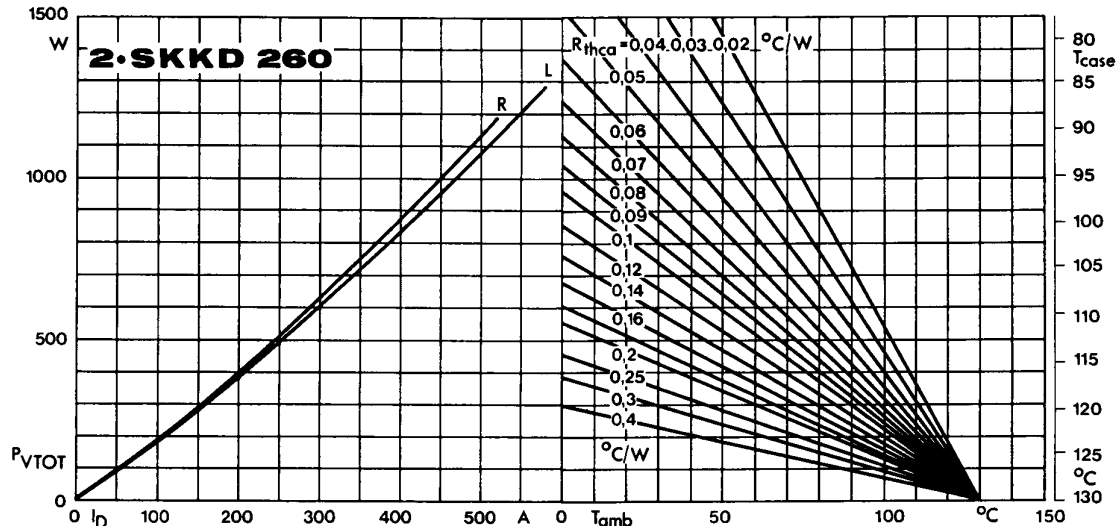


Fig. 12 b Power dissipation of two modules vs. direct current and case temperature

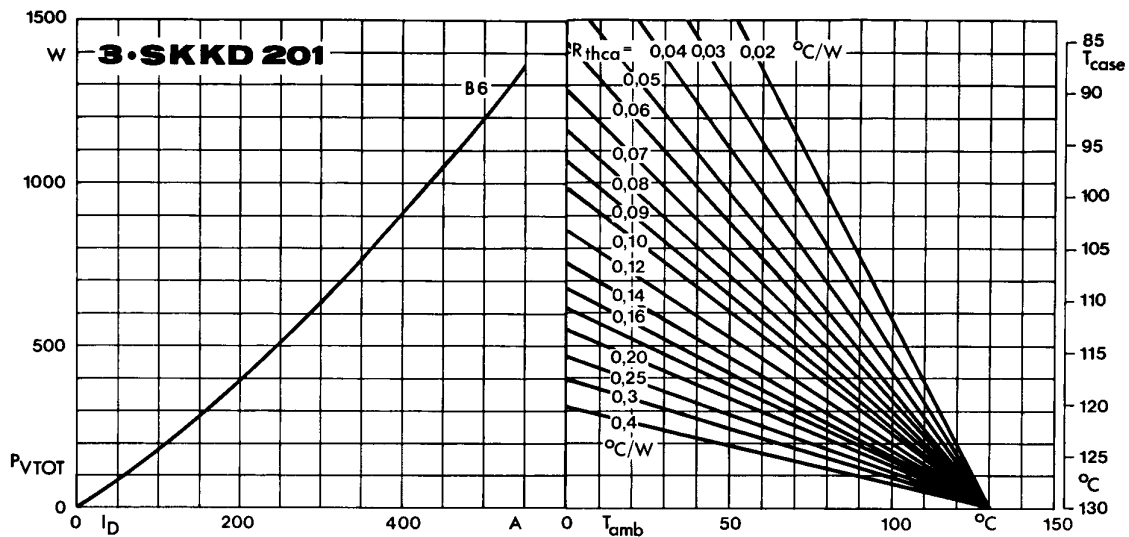


Fig. 13 a Power dissipation of three modules vs. direct current and case temperature

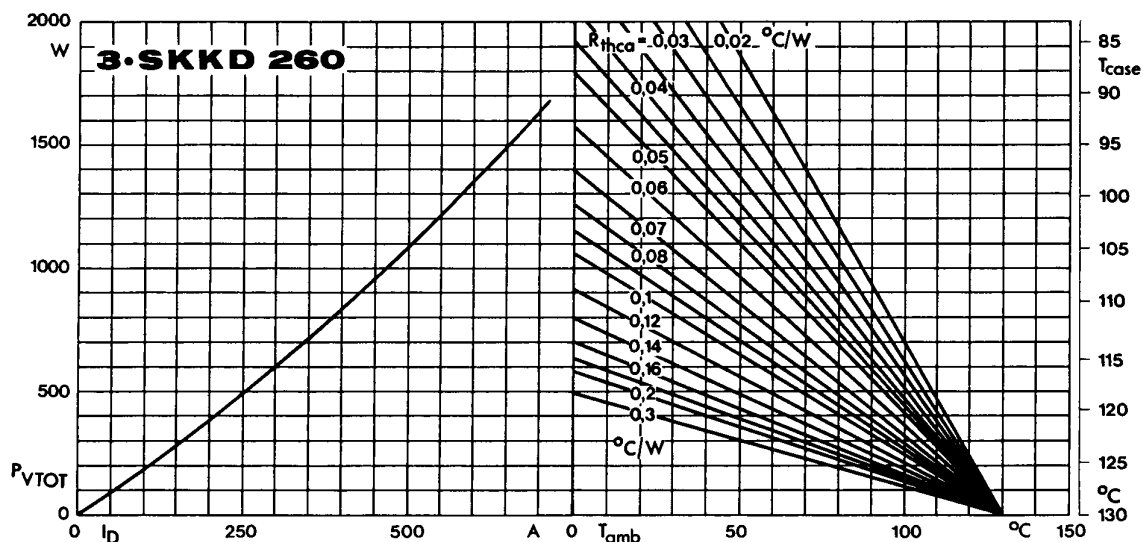


Fig. 13 b Power dissipation of three modules vs. direct current and case temperature

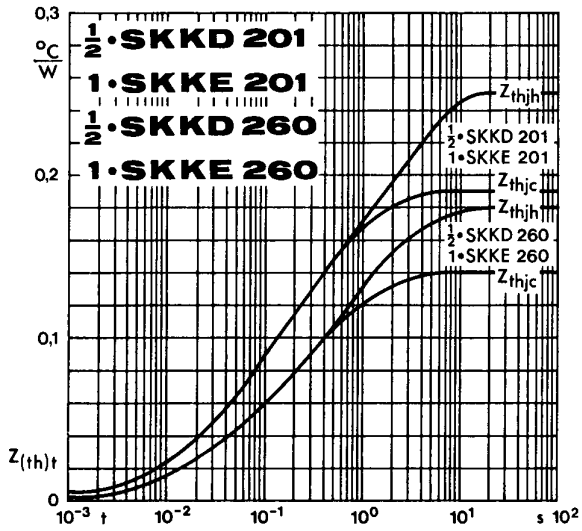


Fig. 14 Transient thermal impedance vs. time

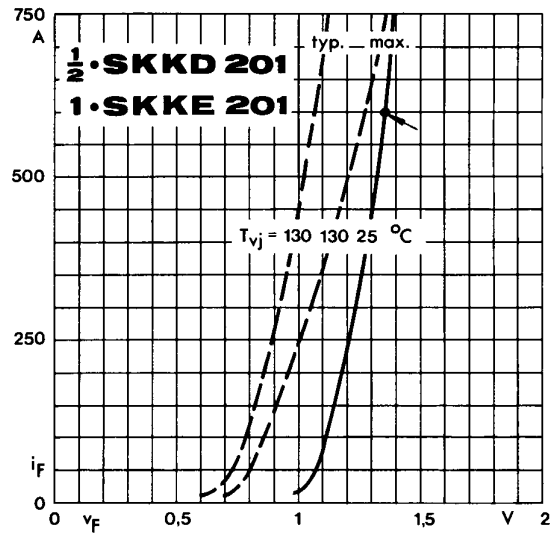


Fig. 15 a Forward characteristics

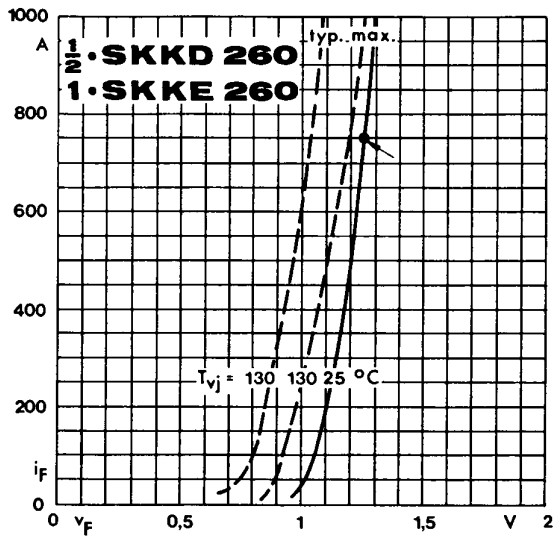


Fig. 15 b Forward characteristics

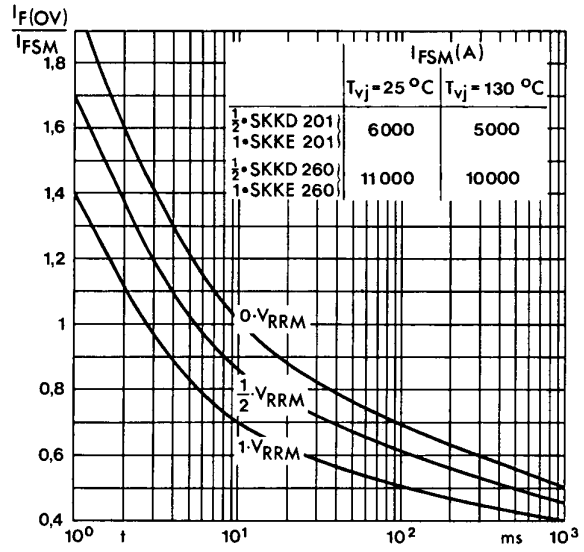
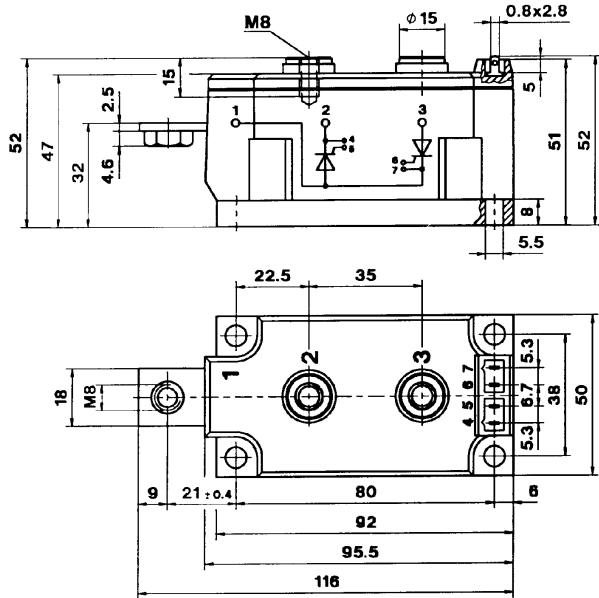


Fig. 16 Surge overload current vs. time

SKKT 131, SKKT 161

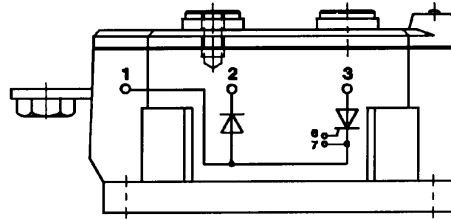
Case A 13

SEMIPACK 3 UL recognized, file no. E 63 532



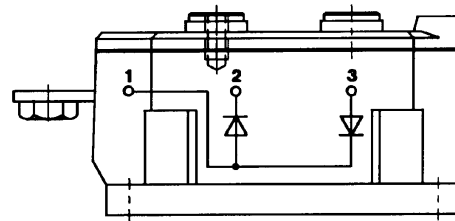
SKKL 131, SKKL 161

Case A 15



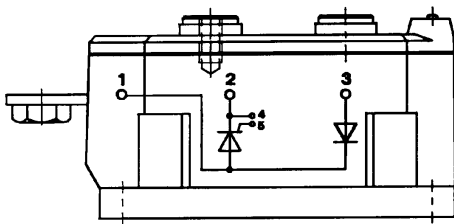
SKKD 201

Case A 16



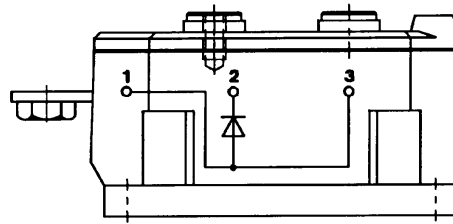
SKKH 131, SKKH 161

Case A 14



SKKE 201

Case A 17



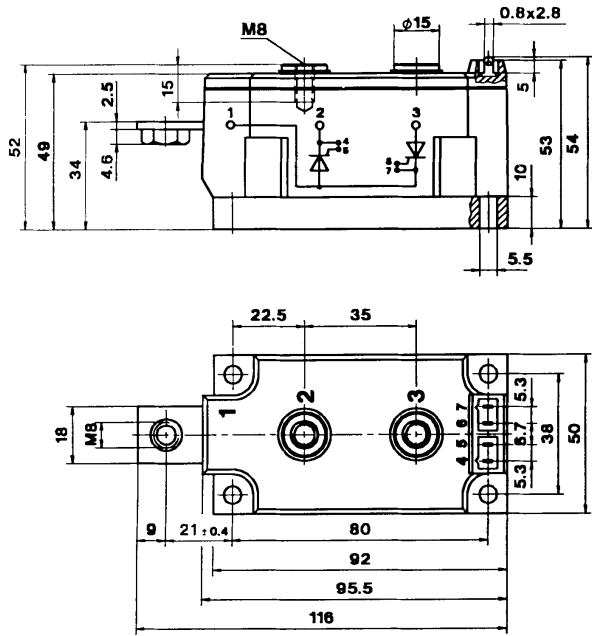
Dimensions in mm

SKKT 210, SKKT 250

Case A 25

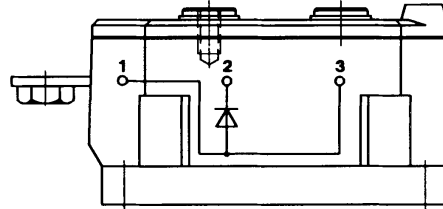
SEMIPACK 3

UL recognized, file no. E 63 532



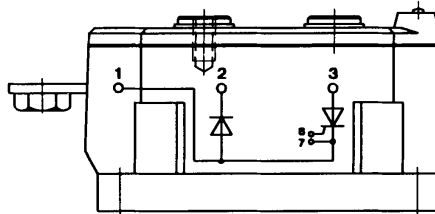
SKKE 260

Case A 28



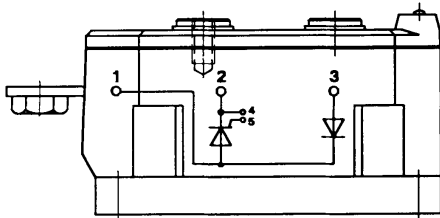
SKKL 210, SKKL 250

Case A 35



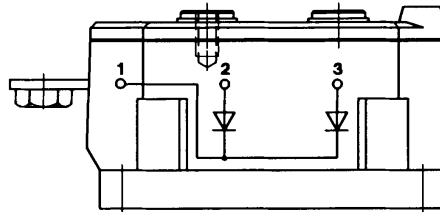
SKKH 210, SKKH 250

Case A 26



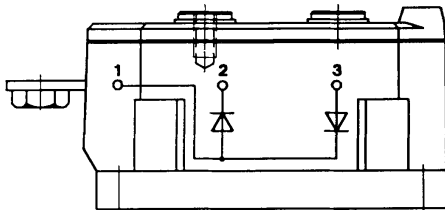
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Case A 58



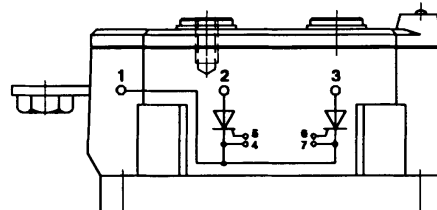
SKKD 260

Case A 27



SKMT 250

Case A 64



Dimensions in mm